

UBP STACKUP INFO

TOTAL BOARD HEIGHT > 2.3mm

BOTH RIGIDS

FLEX

GT0 - Top Overlay / Description
 GTS - Top Soldermask
 GB0 - Bottom Overlay / Description
 GBS - Bottom Soldermask
 GM1 - PCB outline
 GM2 - (this layer) Stack information

Thickness	Er	Layer	Target Impedance	Description	Description	Thickness	Er	Target Impedance
12u-18u	3.5			SolderMask				
18u+18u		1 - GTL	Microstrip 50 Ohm Edge Coupled Microstrip 100 Ohm	Copper				
135u	4.2			FR4 ITI80-A / SI000-2 0.135mm 18u/18u				
18u		2 - GPI	Reference Plane	Copper				
50u	3.7			UT-47PP 106NF-68 / 106LF-72				
50u	3.7			UT-47PP 106NF-68 / 106LF-72				
50u	3.7			UT-47PP 106NF-68 / 106LF-72				
18u		3 - GI	Offset Stripline 50 Ohm Edge Coupled Offset Stripline 100 Ohm	Copper	Shengyi SF302C 1025	25-50u 18u	3.0	Microstrip 50 Ohm Edge Coupled Microstrip 100 Ohm
75u	3.0			DuPont AP 8535R (Adhesiveless, ED copper)	DuPont AP 8535R (Adhesiveless, ED copper)	75u	3.0	
18u		4 - GP2	Reference Plane	Copper		18u		Reference Plane
50u	3.7			UT-47PP 106NF-68 / 106LF-72	Shengyi SF302C 1025	25-50u	3.0	
50u	3.7			UT-47PP 106NF-68 / 106LF-72				
50u	3.7			UT-47PP 106NF-68 / 106LF-72				
1300u	4.2			FR4 ITI80-A / SI000-2 1.3mm No-Copper	AIR - NO FR4 AIR - NO FR4			
50u	3.7			UT-47PP 106NF-68 / 106LF-72				
50u	3.7			UT-47PP 106NF-68 / 106LF-72				
50u	3.7			UT-47PP 106NF-68 / 106LF-72	Shengyi SF302C 1025	25-50u 18u	3.0	Reference Plane
18u		5 - GP3	Reference Plane	Copper	DuPont AP 8535R (Adhesiveless, ED copper)	75u	3.0	
75u	3.0			DuPont AP 8535R (Adhesiveless, ED copper)		18u		Microstrip 50 Ohm Edge Coupled Microstrip 100 Ohm
18u		6 - G2	Offset Stripline 50 Ohm Edge Coupled Offset Stripline 100 Ohm	Copper	Shengyi SF302C 1025	25-50u	3.0	
50u	3.7			UT-47PP 106NF-68 / 106LF-72				
50u	3.7			UT-47PP 106NF-68 / 106LF-72				
50u	3.7			UT-47PP 106NF-68 / 106LF-72				
18u		7 - GP4	Reference Plane	Copper				
135u	4.2			FR4 ITI80-A / SI000-2 0.135mm 18u/18u				
18u+18u		8 - GBL	Microstrip 50 Ohm Edge Coupled Microstrip 100 Ohm	Copper				
12u-18u	3.5			SolderMask				

